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### Understanding [Embedded - FPGAs \(Field Programmable Gate Array\)](#)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

### Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

#### Details

Product Status	Obsolete
Number of LABs/CLBs	225400
Number of Logic Elements/Cells	597000
Total RAM Bits	53248000
Number of I/O	432
Number of Gates	-
Voltage - Supply	0.82V ~ 0.88V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	1517-FBGA (40x40)
Supplier Device Package	1517-FBGA (40x40)
Purchase URL	<a href="https://www.e-xfl.com/product-detail/intel/5sgxeb6r1f40c2l">https://www.e-xfl.com/product-detail/intel/5sgxeb6r1f40c2l</a>

**Table 1. Stratix V GX and GS Commercial and Industrial Speed Grade Offering <sup>(1), (2), (3)</sup> (Part 2 of 2)**

Transceiver Speed Grade	Core Speed Grade							
	C1	C2, C2L	C3	C4	I2, I2L	I3, I3L	I3YY	I4
3 GX channel—8.5 Gbps	—	Yes	Yes	Yes	—	Yes	Yes <sup>(4)</sup>	Yes

**Notes to Table 1:**

- (1) C = Commercial temperature grade; I = Industrial temperature grade.  
 (2) Lower number refers to faster speed grade.  
 (3) C2L, I2L, and I3L speed grades are for low-power devices.  
 (4) I3YY speed grades can achieve up to 10.3125 Gbps.

Table 2 lists the industrial and commercial speed grades for the Stratix V GT devices.

**Table 2. Stratix V GT Commercial and Industrial Speed Grade Offering <sup>(1), (2)</sup>**

Transceiver Speed Grade	Core Speed Grade			
	C1	C2	I2	I3
2 GX channel—12.5 Gbps GT channel—28.05 Gbps	Yes	Yes	—	—
3 GX channel—12.5 Gbps GT channel—25.78 Gbps	Yes	Yes	Yes	Yes

**Notes to Table 2:**

- (1) C = Commercial temperature grade; I = Industrial temperature grade.  
 (2) Lower number refers to faster speed grade.

**Absolute Maximum Ratings**

Absolute maximum ratings define the maximum operating conditions for Stratix V devices. The values are based on experiments conducted with the devices and theoretical modeling of breakdown and damage mechanisms. The functional operation of the device is not implied for these conditions.



Conditions other than those listed in Table 3 may cause permanent damage to the device. Additionally, device operation at the absolute maximum ratings for extended periods of time may have adverse effects on the device.

**Table 3. Absolute Maximum Ratings for Stratix V Devices (Part 1 of 2)**

Symbol	Description	Minimum	Maximum	Unit
V <sub>CC</sub>	Power supply for core voltage and periphery circuitry	−0.5	1.35	V
V <sub>CCPT</sub>	Power supply for programmable power technology	−0.5	1.8	V
V <sub>CCPGM</sub>	Power supply for configuration pins	−0.5	3.9	V
V <sub>CC_AUX</sub>	Auxiliary supply for the programmable power technology	−0.5	3.4	V
V <sub>CCBAT</sub>	Battery back-up power supply for design security volatile key register	−0.5	3.9	V
V <sub>CCPD</sub>	I/O pre-driver power supply	−0.5	3.9	V
V <sub>CCIO</sub>	I/O power supply	−0.5	3.9	V

Table 5 lists the maximum allowed input overshoot voltage and the duration of the overshoot voltage as a percentage of device lifetime. The maximum allowed overshoot duration is specified as a percentage of high time over the lifetime of the device. A DC signal is equivalent to 100% of the duty cycle. For example, a signal that overshoots to 3.95 V can be at 3.95 V for only ~21% over the lifetime of the device; for a device lifetime of 10 years, the overshoot duration amounts to ~2 years.

**Table 5. Maximum Allowed Overshoot During Transitions**

Symbol	Description	Condition (V)	Overshoot Duration as % @ $T_J = 100^{\circ}\text{C}$	Unit
$V_i$ (AC)	AC input voltage	3.8	100	%
		3.85	64	%
		3.9	36	%
		3.95	21	%
		4	12	%
		4.05	7	%
		4.1	4	%
		4.15	2	%
		4.2	1	%

**Figure 1. Stratix V Device Overshoot Duration**



**Table 6. Recommended Operating Conditions for Stratix V Devices (Part 2 of 2)**

Symbol	Description	Condition	Min <sup>(4)</sup>	Typ	Max <sup>(4)</sup>	Unit
t <sub>RAMP</sub>	Power supply ramp time	Standard POR	200 $\mu$ s	—	100 ms	—
		Fast POR	200 $\mu$ s	—	4 ms	—

**Notes to Table 6:**

- (1) V<sub>CCPD</sub> must be 2.5 V when V<sub>CCIO</sub> is 2.5, 1.8, 1.5, 1.35, 1.25 or 1.2 V. V<sub>CCPD</sub> must be 3.0 V when V<sub>CCIO</sub> is 3.0 V.
- (2) If you do not use the design security feature in Stratix V devices, connect V<sub>CCBAT</sub> to a 1.2- to 3.0-V power supply. Stratix V power-on-reset (POR) circuitry monitors V<sub>CCBAT</sub>. Stratix V devices will not exit POR if V<sub>CCBAT</sub> stays at logic low.
- (3) C2L and I2L can also be run at 0.90 V for legacy boards that were designed for the C2 and I2 speed grades.
- (4) The power supply value describes the budget for the DC (static) power supply tolerance and does not include the dynamic tolerance requirements. Refer to the PDN tool for the additional budget for the dynamic tolerance requirements.

Table 7 lists the transceiver power supply recommended operating conditions for Stratix V GX, GS, and GT devices.

**Table 7. Recommended Transceiver Power Supply Operating Conditions for Stratix V GX, GS, and GT Devices (Part 1 of 2)**

Symbol	Description	Devices	Minimum <sup>(4)</sup>	Typical	Maximum <sup>(4)</sup>	Unit
V <sub>CCA_GXBL</sub> (1), (3)	Transceiver channel PLL power supply (left side)	GX, GS, GT	2.85	3.0	3.15	V
			2.375	2.5	2.625	
V <sub>CCA_GXBR</sub> (1), (3)	Transceiver channel PLL power supply (right side)	GX, GS	2.85	3.0	3.15	V
			2.375	2.5	2.625	
V <sub>CCA_GTBR</sub>	Transceiver channel PLL power supply (right side)	GT	2.85	3.0	3.15	V
V <sub>CCHIP_L</sub>	Transceiver hard IP power supply (left side; C1, C2, I2, and I3YY speed grades)	GX, GS, GT	0.87	0.9	0.93	V
	Transceiver hard IP power supply (left side; C2L, C3, C4, I2L, I3, I3L, and I4 speed grades)	GX, GS, GT	0.82	0.85	0.88	V
V <sub>CCHIP_R</sub>	Transceiver hard IP power supply (right side; C1, C2, I2, and I3YY speed grades)	GX, GS, GT	0.87	0.9	0.93	V
	Transceiver hard IP power supply (right side; C2L, C3, C4, I2L, I3, I3L, and I4 speed grades)	GX, GS, GT	0.82	0.85	0.88	V
V <sub>CCHSSI_L</sub>	Transceiver PCS power supply (left side; C1, C2, I2, and I3YY speed grades)	GX, GS, GT	0.87	0.9	0.93	V
	Transceiver PCS power supply (left side; C2L, C3, C4, I2L, I3, I3L, and I4 speed grades)	GX, GS, GT	0.82	0.85	0.88	V
V <sub>CCHSSI_R</sub>	Transceiver PCS power supply (right side; C1, C2, I2, and I3YY speed grades)	GX, GS, GT	0.87	0.9	0.93	V
	Transceiver PCS power supply (right side; C2L, C3, C4, I2L, I3, I3L, and I4 speed grades)	GX, GS, GT	0.82	0.85	0.88	V
V <sub>CCR_GXBL</sub> (2)	Receiver analog power supply (left side)	GX, GS, GT	0.82	0.85	0.88	V
			0.87	0.90	0.93	
			0.97	1.0	1.03	
			1.03	1.05	1.07	

**Table 7. Recommended Transceiver Power Supply Operating Conditions for Stratix V GX, GS, and GT Devices (Part 2 of 2)**

Symbol	Description	Devices	Minimum <sup>(4)</sup>	Typical	Maximum <sup>(4)</sup>	Unit
$V_{CCR\_GXBR}$ (2)	Receiver analog power supply (right side)	GX, GS, GT	0.82	0.85	0.88	V
			0.87	0.90	0.93	
			0.97	1.0	1.03	
			1.03	1.05	1.07	
$V_{CCR\_GTBR}$	Receiver analog power supply for GT channels (right side)	GT	1.02	1.05	1.08	V
$V_{CCT\_GXBL}$ (2)	Transmitter analog power supply (left side)	GX, GS, GT	0.82	0.85	0.88	V
			0.87	0.90	0.93	
			0.97	1.0	1.03	
			1.03	1.05	1.07	
$V_{CCT\_GXBR}$ (2)	Transmitter analog power supply (right side)	GX, GS, GT	0.82	0.85	0.88	V
			0.87	0.90	0.93	
			0.97	1.0	1.03	
			1.03	1.05	1.07	
$V_{CCT\_GTBR}$	Transmitter analog power supply for GT channels (right side)	GT	1.02	1.05	1.08	V
$V_{CCL\_GTBR}$	Transmitter clock network power supply	GT	1.02	1.05	1.08	V
$V_{CCH\_GXBL}$	Transmitter output buffer power supply (left side)	GX, GS, GT	1.425	1.5	1.575	V
$V_{CCH\_GXBR}$	Transmitter output buffer power supply (right side)	GX, GS, GT	1.425	1.5	1.575	V

**Notes to Table 7:**

- (1) This supply must be connected to 3.0 V if the CMU PLL, receiver CDR, or both, are configured at a base data rate > 6.5 Gbps. Up to 6.5 Gbps, you can connect this supply to either 3.0 V or 2.5 V.
- (2) Refer to Table 8 to select the correct power supply level for your design.
- (3) When using ATX PLLs, the supply must be 3.0 V.
- (4) This value describes the budget for the DC (static) power supply tolerance and does not include the dynamic tolerance requirements. Refer to the PDN tool for the additional budget for the dynamic tolerance requirements.

### I/O Pin Leakage Current

Table 9 lists the Stratix V I/O pin leakage current specifications.

**Table 9. I/O Pin Leakage Current for Stratix V Devices <sup>(1)</sup>**

Symbol	Description	Conditions	Min	Typ	Max	Unit
$I_I$	Input pin	$V_I = 0 \text{ V to } V_{CCIOMAX}$	-30	—	30	$\mu\text{A}$
$I_{OZ}$	Tri-stated I/O pin	$V_O = 0 \text{ V to } V_{CCIOMAX}$	-30	—	30	$\mu\text{A}$

**Note to Table 9:**

(1) If  $V_O = V_{CCIO}$  to  $V_{CCIOMAX}$ , 100  $\mu\text{A}$  of leakage current per I/O is expected.

### Bus Hold Specifications

Table 10 lists the Stratix V device family bus hold specifications.

**Table 10. Bus Hold Parameters for Stratix V Devices**

Parameter	Symbol	Conditions	V <sub>CCIO</sub>										Unit
			1.2 V		1.5 V		1.8 V		2.5 V		3.0 V		
			Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	
Low sustaining current	I <sub>SUSL</sub>	V <sub>IN</sub> > V <sub>IL</sub> (maximum)	22.5	—	25.0	—	30.0	—	50.0	—	70.0	—	μA
High sustaining current	I <sub>SUSH</sub>	V <sub>IN</sub> < V <sub>IH</sub> (minimum)	−22.5	—	−25.0	—	−30.0	—	−50.0	—	−70.0	—	μA
Low overdrive current	I <sub>ODL</sub>	0V < V <sub>IN</sub> < V <sub>CCIO</sub>	—	120	—	160	—	200	—	300	—	500	μA
High overdrive current	I <sub>ODH</sub>	0V < V <sub>IN</sub> < V <sub>CCIO</sub>	—	−120	—	−160	—	−200	—	−300	—	−500	μA
Bus-hold trip point	V <sub>TRIP</sub>	—	0.45	0.95	0.50	1.00	0.68	1.07	0.70	1.70	0.80	2.00	V

### On-Chip Termination (OCT) Specifications

If you enable OCT calibration, calibration is automatically performed at power-up for I/Os connected to the calibration block. Table 11 lists the Stratix V OCT termination calibration accuracy specifications.

**Table 11. OCT Calibration Accuracy Specifications for Stratix V Devices <sup>(1)</sup> (Part 1 of 2)**

Symbol	Description	Conditions	Calibration Accuracy				Unit
			C1	C2,I2	C3,I3, I3YY	C4,I4	
25- $\Omega$ $R_S$	Internal series termination with calibration (25- $\Omega$ setting)	$V_{CCIO} = 3.0, 2.5, 1.8, 1.5, 1.2 \text{ V}$	$\pm 15$	$\pm 15$	$\pm 15$	$\pm 15$	%

**Table 12. OCT Without Calibration Resistance Tolerance Specifications for Stratix V Devices (Part 2 of 2)**

Symbol	Description	Conditions	Resistance Tolerance				Unit
			C1	C2, I2	C3, I3, I3YY	C4, I4	
50-Ω R <sub>S</sub>	Internal series termination without calibration (50-Ω setting)	V <sub>CCIO</sub> = 1.8 and 1.5 V	±30	±30	±40	±40	%
50-Ω R <sub>S</sub>	Internal series termination without calibration (50-Ω setting)	V <sub>CCIO</sub> = 1.2 V	±35	±35	±50	±50	%
100-Ω R <sub>D</sub>	Internal differential termination (100-Ω setting)	V <sub>CCPD</sub> = 2.5 V	±25	±25	±25	±25	%

Calibration accuracy for the calibrated series and parallel OCTs are applicable at the moment of calibration. When voltage and temperature conditions change after calibration, the tolerance may change.

OCT calibration is automatically performed at power-up for OCT-enabled I/Os. Table 13 lists the OCT variation with temperature and voltage after power-up calibration. Use Table 13 to determine the OCT variation after power-up calibration and Equation 1 to determine the OCT variation without recalibration.

**Equation 1. OCT Variation Without Recalibration for Stratix V Devices <sup>(1), (2), (3), (4), (5), (6)</sup>**

$$R_{OCT} = R_{SCAL} \left( 1 + \left\langle \frac{dR}{dT} \times \Delta T \right\rangle \pm \left\langle \frac{dR}{dV} \times \Delta V \right\rangle \right)$$

**Notes to Equation 1:**

- (1) The R<sub>OCT</sub> value shows the range of OCT resistance with the variation of temperature and V<sub>CCIO</sub>.
- (2) R<sub>SCAL</sub> is the OCT resistance value at power-up.
- (3) ΔT is the variation of temperature with respect to the temperature at power-up.
- (4) ΔV is the variation of voltage with respect to the V<sub>CCIO</sub> at power-up.
- (5) dR/dT is the percentage change of R<sub>SCAL</sub> with temperature.
- (6) dR/dV is the percentage change of R<sub>SCAL</sub> with voltage.

Table 13 lists the on-chip termination variation after power-up calibration.

**Table 13. OCT Variation after Power-Up Calibration for Stratix V Devices (Part 1 of 2) <sup>(1)</sup>**

Symbol	Description	V <sub>CCIO</sub> (V)	Typical	Unit
dR/dV	OCT variation with voltage without recalibration	3.0	0.0297	% / mV
		2.5	0.0344	
		1.8	0.0499	
		1.5	0.0744	
		1.2	0.1241	

**Table 21. Differential HSTL and HSUL I/O Standards for Stratix V Devices (Part 2 of 2)**

I/O Standard	$V_{CCIO}$ (V)			$V_{DIF(DC)}$ (V)		$V_{X(AC)}$ (V)			$V_{CM(DC)}$ (V)			$V_{DIF(AC)}$ (V)	
	Min	Typ	Max	Min	Max	Min	Typ	Max	Min	Typ	Max	Min	Max
HSTL-12 Class I, II	1.14	1.2	1.26	0.16	$V_{CCIO} + 0.3$	—	$0.5^* V_{CCIO}$	—	$0.4^* V_{CCIO}$	$0.5^* V_{CCIO}$	$0.6^* V_{CCIO}$	0.3	$V_{CCIO} + 0.48$
HSUL-12	1.14	1.2	1.3	0.26	0.26	$0.5^* V_{CCIO} - 0.12$	$0.5^* V_{CCIO}$	$0.5^* V_{CCIO} + 0.12$	$0.4^* V_{CCIO}$	$0.5^* V_{CCIO}$	$0.6^* V_{CCIO}$	0.44	0.44

**Table 22. Differential I/O Standard Specifications for Stratix V Devices <sup>(7)</sup>**

I/O Standard	$V_{CCIO}$ (V) <sup>(10)</sup>			$V_{ID}$ (mV) <sup>(8)</sup>			$V_{ICM(DC)}$ (V)			$V_{OD}$ (V) <sup>(6)</sup>			$V_{OCM}$ (V) <sup>(6)</sup>		
	Min	Typ	Max	Min	Condition	Max	Min	Condition	Max	Min	Typ	Max	Min	Typ	Max
PCML	Transmitter, receiver, and input reference clock pins of the high-speed transceivers use the PCML I/O standard. For transmitter, receiver, and reference clock I/O pin specifications, refer to Table 23 on page 18.														
2.5 V LVDS <sup>(1)</sup>	2.375	2.5	2.625	100	$V_{CM} = 1.25$ V	—	0.05	$D_{MAX} \leq 700$ Mbps	1.8	0.247	—	0.6	1.125	1.25	1.375
						—	1.05	$D_{MAX} > 700$ Mbps	1.55	0.247	—	0.6	1.125	1.25	1.375
BLVDS <sup>(5)</sup>	2.375	2.5	2.625	100	—	—	—	—	—	—	—	—	—	—	—
RSDS (HIO) <sup>(2)</sup>	2.375	2.5	2.625	100	$V_{CM} = 1.25$ V	—	0.3	—	1.4	0.1	0.2	0.6	0.5	1.2	1.4
Mini-LVDS (HIO) <sup>(3)</sup>	2.375	2.5	2.625	200	—	600	0.4	—	1.325	0.25	—	0.6	1	1.2	1.4
LVPECL <sup>(4), (9)</sup>	—	—	—	300	—	—	0.6	$D_{MAX} \leq 700$ Mbps	1.8	—	—	—	—	—	—
	—	—	—	300	—	—	1	$D_{MAX} > 700$ Mbps	1.6	—	—	—	—	—	—

**Notes to Table 22:**

- (1) For optimized LVDS receiver performance, the receiver voltage input range must be between 1.0 V to 1.6 V for data rates above 700 Mbps, and 0 V to 1.85 V for data rates below 700 Mbps.
- (2) For optimized RSDS receiver performance, the receiver voltage input range must be between 0.25 V to 1.45 V.
- (3) For optimized Mini-LVDS receiver performance, the receiver voltage input range must be between 0.3 V to 1.425 V.
- (4) For optimized LVPECL receiver performance, the receiver voltage input range must be between 0.85 V to 1.75 V for data rate above 700 Mbps and 0.45 V to 1.95 V for data rate below 700 Mbps.
- (5) There are no fixed  $V_{ICM}$ ,  $V_{OD}$ , and  $V_{OCM}$  specifications for BLVDS. They depend on the system topology.
- (6) RL range:  $90 \leq RL \leq 110 \Omega$ .
- (7) The 1.4-V and 1.5-V PCML transceiver I/O standard specifications are described in "Transceiver Performance Specifications" on page 18.
- (8) The minimum VID value is applicable over the entire common mode range, VCM.
- (9) LVPECL is only supported on dedicated clock input pins.
- (10) Differential inputs are powered by VCCPD which requires 2.5 V.

## Power Consumption

Altera offers two ways to estimate power consumption for a design—the Excel-based Early Power Estimator and the Quartus® II PowerPlay Power Analyzer feature.



## Switching Characteristics

This section provides performance characteristics of the Stratix V core and periphery blocks.

These characteristics can be designated as Preliminary or Final.

- Preliminary characteristics are created using simulation results, process data, and other known parameters. The title of these tables show the designation as “Preliminary.”
- Final numbers are based on actual silicon characterization and testing. The numbers reflect the actual performance of the device under worst-case silicon process, voltage, and junction temperature conditions. There are no designations on finalized tables.

### Transceiver Performance Specifications

This section describes transceiver performance specifications.

Table 23 lists the Stratix V GX and GS transceiver specifications.

**Table 23. Transceiver Specifications for Stratix V GX and GS Devices <sup>(1)</sup> (Part 1 of 7)**

Symbol/ Description	Conditions	Transceiver Speed Grade 1			Transceiver Speed Grade 2			Transceiver Speed Grade 3			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
Reference Clock											
Supported I/O Standards	Dedicated reference clock pin	1.2-V PCML, 1.4-V PCML, 1.5-V PCML, 2.5-V PCML, Differential LVPECL, LVDS, and HCSL									
	RX reference clock pin	1.4-V PCML, 1.5-V PCML, 2.5-V PCML, LVPECL, and LVDS									
Input Reference Clock Frequency (CMU PLL) <sup>(8)</sup>	—	40	—	710	40	—	710	40	—	710	MHz
Input Reference Clock Frequency (ATX PLL) <sup>(8)</sup>	—	100	—	710	100	—	710	100	—	710	MHz
Rise time	Measure at ±60 mV of differential signal <sup>(26)</sup>	—	—	400	—	—	400	—	—	400	ps
Fall time	Measure at ±60 mV of differential signal <sup>(26)</sup>	—	—	400	—	—	400	—	—	400	
Duty cycle	—	45	—	55	45	—	55	45	—	55	%
Spread-spectrum modulating clock frequency	PCI Express® (PCIe®)	30	—	33	30	—	33	30	—	33	kHz

Table 24 shows the maximum transmitter data rate for the clock network.

**Table 24. Clock Network Maximum Data Rate Transmitter Specifications <sup>(1)</sup>**

Clock Network	ATX PLL			CMU PLL <sup>(2)</sup>			fPLL		
	Non-bonded Mode (Gbps)	Bonded Mode (Gbps)	Channel Span	Non-bonded Mode (Gbps)	Bonded Mode (Gbps)	Channel Span	Non-bonded Mode (Gbps)	Bonded Mode (Gbps)	Channel Span
x1 <sup>(3)</sup>	14.1	—	6	12.5	—	6	3.125	—	3
x6 <sup>(3)</sup>	—	14.1	6	—	12.5	6	—	3.125	6
x6 PLL Feedback <sup>(4)</sup>	—	14.1	Side-wide	—	12.5	Side-wide	—	—	—
xN (PCIe)	—	8.0	8	—	5.0	8	—	—	—
xN (Native PHY IP)	8.0	8.0	Up to 13 channels above and below PLL	7.99	7.99	Up to 13 channels above and below PLL	3.125	3.125	Up to 13 channels above and below PLL
	—	8.01 to 9.8304	Up to 7 channels above and below PLL						

**Notes to Table 24:**

- (1) Valid data rates below the maximum specified in this table depend on the reference clock frequency and the PLL counter settings. Check the MegaWizard message during the PHY IP instantiation.
- (2) ATX PLL is recommended at 8 Gbps and above data rates for improved jitter performance.
- (3) Channel span is within a transceiver bank.
- (4) Side-wide channel bonding is allowed up to the maximum supported by the PHY IP.

**Table 28. Transceiver Specifications for Stratix V GT Devices (Part 1 of 5) <sup>(1)</sup>**

Symbol/ Description	Conditions	Transceiver Speed Grade 2			Transceiver Speed Grade 3			Unit
		Min	Typ	Max	Min	Typ	Max	
Reference Clock								
Supported I/O Standards	Dedicated reference clock pin	1.2-V PCML, 1.4-V PCML, 1.5-V PCML, 2.5-V PCML, Differential LVPECL, LVDS, and HCSL						
	RX reference clock pin	1.4-V PCML, 1.5-V PCML, 2.5-V PCML, LVPECL, and LVDS						
Input Reference Clock Frequency (CMU PLL) <sup>(6)</sup>	—	40	—	710	40	—	710	MHz
Input Reference Clock Frequency (ATX PLL) <sup>(6)</sup>	—	100	—	710	100	—	710	MHz
Rise time	20% to 80%	—	—	400	—	—	400	ps
Fall time	80% to 20%	—	—	400	—	—	400	
Duty cycle	—	45	—	55	45	—	55	%
Spread-spectrum modulating clock frequency	PCI Express (PCIe)	30	—	33	30	—	33	kHz
Spread-spectrum downspread	PCIe	—	0 to −0.5	—	—	0 to −0.5	—	%
On-chip termination resistors <sup>(19)</sup>	—	—	100	—	—	100	—	Ω
Absolute V <sub>MAX</sub> <sup>(3)</sup>	Dedicated reference clock pin	—	—	1.6	—	—	1.6	V
	RX reference clock pin	—	—	1.2	—	—	1.2	
Absolute V <sub>MIN</sub>	—	-0.4	—	—	-0.4	—	—	V
Peak-to-peak differential input voltage	—	200	—	1600	200	—	1600	mV
V <sub>ICM</sub> (AC coupled)	Dedicated reference clock pin	1050/1000 <sup>(2)</sup>			1050/1000 <sup>(2)</sup>			mV
	RX reference clock pin	1.0/0.9/0.85 <sup>(22)</sup>			1.0/0.9/0.85 <sup>(22)</sup>			V
V <sub>ICM</sub> (DC coupled)	HCSL I/O standard for PCIe reference clock	250	—	550	250	—	550	mV

Figure 4 shows the differential transmitter output waveform.

**Figure 4. Differential Transmitter/Receiver Output/Input Waveform**



Figure 5 shows the Stratix V AC gain curves for GT channels.

**Figure 5. AC Gain Curves for GT Channels**

- XFI
- ASI
- HiGig/HiGig+
- HiGig2/HiGig2+
- Serial Data Converter (SDC)
- GPON
- SDI
- SONET
- Fibre Channel (FC)
- PCIe
- QPI
- SFF-8431

Download the Stratix V Characterization Report Tool to view the characterization report summary for these protocols.

## Core Performance Specifications

This section describes the clock tree, phase-locked loop (PLL), digital signal processing (DSP), memory blocks, configuration, and JTAG specifications.

### Clock Tree Specifications

Table 30 lists the clock tree specifications for Stratix V devices.

**Table 30. Clock Tree Performance for Stratix V Devices <sup>(1)</sup>**

Symbol	Performance			Unit
	C1, C2, C2L, I2, and I2L	C3, I3, I3L, and I3YY	C4, I4	
Global and Regional Clock	717	650	580	MHz
Periphery Clock	550	500	500	MHz

**Note to Table 30:**

(1) The Stratix V ES devices are limited to 600 MHz core clock tree performance.

## Periphery Performance

This section describes periphery performance, including high-speed I/O and external memory interface.

I/O performance supports several system interfaces, such as the **LVDS** high-speed I/O interface, external memory interface, and the **PCI/PCI-X** bus interface.

General-purpose I/O standards such as 3.3-, 2.5-, 1.8-, and 1.5-**LVTTL/LVCMOS** are capable of a typical 167 MHz and 1.2-**LVCMOS** at 100 MHz interfacing frequency with a 10 pF load.



The actual achievable frequency depends on design- and system-specific factors. Ensure proper timing closure in your design and perform HSPICE/IBIS simulations based on your specific design and system setup to determine the maximum achievable frequency in your system.

### High-Speed I/O Specification

Table 36 lists high-speed I/O timing for Stratix V devices.

**Table 36. High-Speed I/O Specifications for Stratix V Devices <sup>(1)</sup>, <sup>(2)</sup> (Part 1 of 4)**

Symbol	Conditions	C1			C2, C2L, I2, I2L			C3, I3, I3L, I3YY			C4,I4			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
$f_{\text{HCLK\_in}}$ (input clock frequency) True Differential I/O Standards	Clock boost factor $W = 1$ to 40 <sup>(4)</sup>	5	—	800	5	—	800	5	—	625	5	—	525	MHz
$f_{\text{HCLK\_in}}$ (input clock frequency) Single Ended I/O Standards <sup>(3)</sup>	Clock boost factor $W = 1$ to 40 <sup>(4)</sup>	5	—	800	5	—	800	5	—	625	5	—	525	MHz
$f_{\text{HCLK\_in}}$ (input clock frequency) Single Ended I/O Standards	Clock boost factor $W = 1$ to 40 <sup>(4)</sup>	5	—	520	5	—	520	5	—	420	5	—	420	MHz
$f_{\text{HCLK\_OUT}}$ (output clock frequency)	—	5	—	800	5	—	800	5	—	625 <sup>(5)</sup>	5	—	525 <sup>(5)</sup>	MHz

Figure 7 shows the dynamic phase alignment (DPA) lock time specifications with the DPA PLL calibration option enabled.

**Figure 7. DPA Lock Time Specification with DPA PLL Calibration Enabled**



Table 37 lists the DPA lock time specifications for Stratix V devices.

**Table 37. DPA Lock Time Specifications for Stratix V GX Devices Only <sup>(1), (2), (3)</sup>**

Standard	Training Pattern	Number of Data Transitions in One Repetition of the Training Pattern	Number of Repetitions per 256 Data Transitions <sup>(4)</sup>	Maximum
SPI-4	00000000001111111111	2	128	640 data transitions
Parallel Rapid I/O	00001111	2	128	640 data transitions
	10010000	4	64	640 data transitions
Miscellaneous	10101010	8	32	640 data transitions
	01010101	8	32	640 data transitions

**Notes to Table 37:**

- (1) The DPA lock time is for one channel.
- (2) One data transition is defined as a 0-to-1 or 1-to-0 transition.
- (3) The DPA lock time stated in this table applies to both commercial and industrial grade.
- (4) This is the number of repetitions for the stated training pattern to achieve the 256 data transitions.

Figure 8 shows the LVDS soft-clock data recovery (CDR)/DPA sinusoidal jitter tolerance specification for a data rate  $\geq 1.25$  Gbps. Table 38 lists the LVDS soft-CDR/DPA sinusoidal jitter tolerance specification for a data rate  $\geq 1.25$  Gbps.

**Figure 8. LVDS Soft-CDR/DPA Sinusoidal Jitter Tolerance Specification for a Data Rate  $\geq 1.25$  Gbps**



**Table 48. Minimum Configuration Time Estimation for Stratix V Devices**

Variant	Member Code	Active Serial <sup>(1)</sup>			Fast Passive Parallel <sup>(2)</sup>		
		Width	DCLK (MHz)	Min Config Time (s)	Width	DCLK (MHz)	Min Config Time (s)
GS	D3	4	100	0.344	32	100	0.043
	D4	4	100	0.534	32	100	0.067
		4	100	0.344	32	100	0.043
	D5	4	100	0.534	32	100	0.067
	D6	4	100	0.741	32	100	0.093
	D8	4	100	0.741	32	100	0.093
E	E9	4	100	0.857	32	100	0.107
	EB	4	100	0.857	32	100	0.107

**Notes to Table 48:**

(1) DCLK frequency of 100 MHz using external CLKUSR.

(2) Max FPGA FPP bandwidth may exceed bandwidth available from some external storage or control logic.

## Fast Passive Parallel Configuration Timing

This section describes the fast passive parallel (FPP) configuration timing parameters for Stratix V devices.

### DCLK-to-DATA[] Ratio for FPP Configuration

FPP configuration requires a different DCLK-to-DATA [] ratio when you enable the design security, decompression, or both features. Table 49 lists the DCLK-to-DATA [] ratio for each combination.

**Table 49. DCLK-to-DATA[] Ratio <sup>(1)</sup> (Part 1 of 2)**

Configuration Scheme	Decompression	Design Security	DCLK-to-DATA[] Ratio
FPP ×8	Disabled	Disabled	1
	Disabled	Enabled	1
	Enabled	Disabled	2
	Enabled	Enabled	2
FPP ×16	Disabled	Disabled	1
	Disabled	Enabled	2
	Enabled	Disabled	4
	Enabled	Enabled	4



**Table 49. DCLK-to-DATA[] Ratio <sup>(1)</sup> (Part 2 of 2)**

Configuration Scheme	Decompression	Design Security	DCLK-to-DATA[] Ratio
FPP ×32	Disabled	Disabled	1
	Disabled	Enabled	4
	Enabled	Disabled	8
	Enabled	Enabled	8

**Note to Table 49:**

- (1) Depending on the DCLK-to-DATA[] ratio, the host must send a DCLK frequency that is r times the data rate in bytes per second (Bps), or words per second (Wps). For example, in FPP ×16 when the DCLK-to-DATA[] ratio is 2, the DCLK frequency must be 2 times the data rate in Wps. Stratix V devices use the additional clock cycles to decrypt and decompress the configuration data.



If the DCLK-to-DATA[] ratio is greater than 1, at the end of configuration, you can only stop the DCLK (DCLK-to-DATA[] ratio – 1) clock cycles after the last data is latched into the Stratix V device.

Figure 11 shows the configuration interface connections between the Stratix V device and a MAX II or MAX V device for single device configuration.

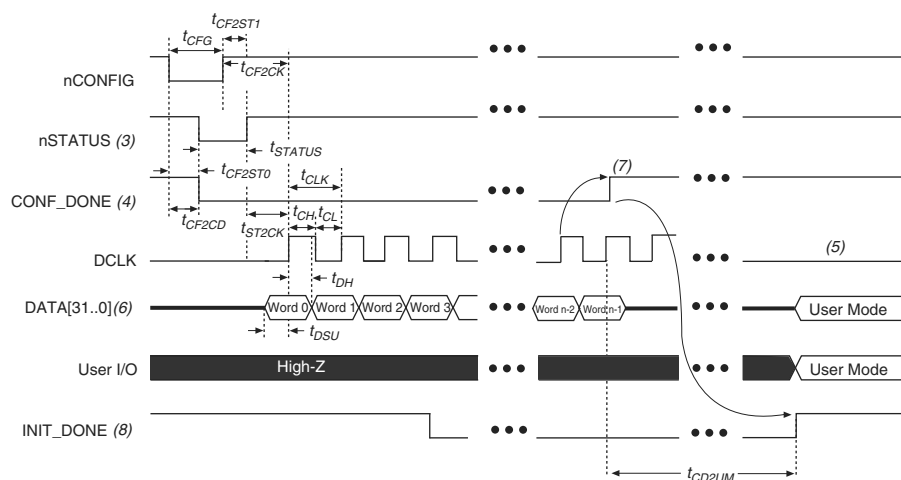
**Figure 11. Single Device FPP Configuration Using an External Host****Notes to Figure 11:**

- (1) Connect the resistor to a supply that provides an acceptable input signal for the Stratix V device.  $V_{CCPGM}$  must be high enough to meet the  $V_{IH}$  specification of the I/O on the device and the external host. Altera recommends powering up all configuration system I/Os with  $V_{CCPGM}$ .
- (2) You can leave the nCEO pin unconnected or use it as a user I/O pin when it does not feed another device's nCE pin.
- (3) The MSEL pin settings vary for different data width, configuration voltage standards, and POR delay. To connect MSEL, refer to the MSEL Pin Settings section of the "Configuration, Design Security, and Remote System Upgrades in Stratix V Devices" chapter.
- (4) If you use FPP ×8, use DATA[7..0]. If you use FPP ×16, use DATA[15..0].

## FPP Configuration Timing when DCLK-to-DATA [] = 1

Figure 12 shows the timing waveform for FPP configuration when using a MAX II or MAX V device as an external host. This waveform shows timing when the DCLK-to-DATA [] ratio is 1.

**Figure 12. FPP Configuration Timing Waveform When the DCLK-to-DATA[] Ratio is 1 <sup>(1), (2)</sup>**



### Notes to Figure 12:

- (1) Use this timing waveform when the DCLK-to-DATA [] ratio is 1.
- (2) The beginning of this waveform shows the device in user mode. In user mode, nCONFIG, nSTATUS, and CONF\_DONE are at logic-high levels. When nCONFIG is pulled low, a reconfiguration cycle begins.
- (3) After power-up, the Stratix V device holds nSTATUS low for the time of the POR delay.
- (4) After power-up, before and during configuration, CONF\_DONE is low.
- (5) Do not leave DCLK floating after configuration. DCLK is ignored after configuration is complete. It can toggle high or low if required.
- (6) For FPP x16, use DATA [15..0]. For FPP x8, use DATA [7..0]. DATA [31..0] are available as a user I/O pin after configuration. The state of this pin depends on the dual-purpose pin settings.
- (7) To ensure a successful configuration, send the entire configuration data to the Stratix V device. CONF\_DONE is released high when the Stratix V device receives all the configuration data successfully. After CONF\_DONE goes high, send two additional falling edges on DCLK to begin initialization and enter user mode.
- (8) After the option bit to enable the INIT\_DONE pin is configured into the device, the INIT\_DONE goes low.

Table 51 lists the timing parameters for Stratix V devices for FPP configuration when the DCLK-to-DATA [ ] ratio is more than 1.

**Table 51. FPP Timing Parameters for Stratix V Devices When the DCLK-to-DATA[ ] Ratio is >1 <sup>(1)</sup>**

Symbol	Parameter	Minimum	Maximum	Units
$t_{CF2CD}$	nCONFIG low to CONF_DONE low	—	600	ns
$t_{CF2ST0}$	nCONFIG low to nSTATUS low	—	600	ns
$t_{CFG}$	nCONFIG low pulse width	2	—	$\mu$ s
$t_{STATUS}$	nSTATUS low pulse width	268	1,506 <sup>(2)</sup>	$\mu$ s
$t_{CF2ST1}$	nCONFIG high to nSTATUS high	—	1,506 <sup>(2)</sup>	$\mu$ s
$t_{CF2CK}$ <sup>(5)</sup>	nCONFIG high to first rising edge on DCLK	1,506	—	$\mu$ s
$t_{ST2CK}$ <sup>(5)</sup>	nSTATUS high to first rising edge of DCLK	2	—	$\mu$ s
$t_{DSU}$	DATA [ ] setup time before rising edge on DCLK	5.5	—	ns
$t_{DH}$	DATA [ ] hold time after rising edge on DCLK	$N-1/f_{DCLK}$ <sup>(5)</sup>	—	s
$t_{CH}$	DCLK high time	$0.45 \times 1/f_{MAX}$	—	s
$t_{CL}$	DCLK low time	$0.45 \times 1/f_{MAX}$	—	s
$t_{CLK}$	DCLK period	$1/f_{MAX}$	—	s
$f_{MAX}$	DCLK frequency (FPP $\times 8/\times 16$ )	—	125	MHz
	DCLK frequency (FPP $\times 32$ )	—	100	MHz
$t_R$	Input rise time	—	40	ns
$t_F$	Input fall time	—	40	ns
$t_{CD2UM}$	CONF_DONE high to user mode <sup>(3)</sup>	175	437	$\mu$ s
$t_{CD2CU}$	CONF_DONE high to CLKUSR enabled	$4 \times$ maximum DCLK period	—	—
$t_{CD2UMC}$	CONF_DONE high to user mode with CLKUSR option on	$t_{CD2CU} + (8576 \times \text{CLKUSR period})$ <sup>(4)</sup>	—	—

**Notes to Table 51:**

- (1) Use these timing parameters when you use the decompression and design security features.
- (2) You can obtain this value if you do not delay configuration by extending the nCONFIG or nSTATUS low pulse width.
- (3) The minimum and maximum numbers apply only if you use the internal oscillator as the clock source for initializing the device.
- (4) To enable the CLKUSR pin as the initialization clock source and to obtain the maximum frequency specification on these pins, refer to the Initialization section of the “Configuration, Design Security, and Remote System Upgrades in Stratix V Devices” chapter.
- (5) N is the DCLK-to-DATA ratio and  $f_{DCLK}$  is the DCLK frequency the system is operating.
- (6) If nSTATUS is monitored, follow the  $t_{ST2CK}$  specification. If nSTATUS is not monitored, follow the  $t_{CF2CK}$  specification.

**Table 53. AS Timing Parameters for AS ×1 and AS ×4 Configurations in Stratix V Devices <sup>(1), (2)</sup> (Part 2 of 2)**

Symbol	Parameter	Minimum	Maximum	Units
$t_{CD2UM}$	CONF_DONE high to user mode <sup>(3)</sup>	175	437	μs
$t_{CD2CU}$	CONF_DONE high to CLKUSR enabled	4 × maximum DCLK period	—	—
$t_{CD2UMC}$	CONF_DONE high to user mode with CLKUSR option on	$t_{CD2CU} + (8576 \times \text{CLKUSR period})$	—	—

**Notes to Table 53:**

- (1) The minimum and maximum numbers apply only if you choose the internal oscillator as the clock source for initializing the device.
- (2)  $t_{CF2CD}$ ,  $t_{CF2ST0}$ ,  $t_{CFG}$ ,  $t_{STATUS}$ , and  $t_{CF2ST1}$  timing parameters are identical to the timing parameters for PS mode listed in Table 54 on page 63.
- (3) To enable the CLKUSR pin as the initialization clock source and to obtain the maximum frequency specification on this pin, refer to the Initialization section of the “Configuration, Design Security, and Remote System Upgrades in Stratix V Devices” chapter.

## Passive Serial Configuration Timing

Figure 15 shows the timing waveform for a passive serial (PS) configuration when using a MAX II device, MAX V device, or microprocessor as an external host.

**Figure 15. PS Configuration Timing Waveform <sup>(1)</sup>****Notes to Figure 15:**

- (1) The beginning of this waveform shows the device in user mode. In user mode, nCONFIG, nSTATUS, and CONF\_DONE are at logic high levels. When nCONFIG is pulled low, a reconfiguration cycle begins.
- (2) After power-up, the Stratix V device holds nSTATUS low for the time of the POR delay.
- (3) After power-up, before and during configuration, CONF\_DONE is low.
- (4) Do not leave DCLK floating after configuration. You can drive it high or low, whichever is more convenient.
- (5) DATA0 is available as a user I/O pin after configuration. The state of this pin depends on the dual-purpose pin settings in the **Device and Pins Option**.
- (6) To ensure a successful configuration, send the entire configuration data to the Stratix V device. CONF\_DONE is released high after the Stratix V device receives all the configuration data successfully. After CONF\_DONE goes high, send two additional falling edges on DCLK to begin initialization and enter user mode.
- (7) After the option bit to enable the INIT\_DONE pin is configured into the device, the INIT\_DONE goes low.

**Table 61. Document Revision History (Part 3 of 3)**

Date	Version	Changes
May 2013	2.7	<ul style="list-style-type: none"> <li>■ Updated Table 2, Table 6, Table 7, Table 20, Table 23, Table 27, Table 47, Table 60</li> <li>■ Added Table 24, Table 48</li> <li>■ Updated Figure 9, Figure 10, Figure 11, Figure 12</li> </ul>
February 2013	2.6	<ul style="list-style-type: none"> <li>■ Updated Table 7, Table 9, Table 20, Table 23, Table 27, Table 30, Table 31, Table 35, Table 46</li> <li>■ Updated “Maximum Allowed Overshoot and Undershoot Voltage”</li> </ul>
December 2012	2.5	<ul style="list-style-type: none"> <li>■ Updated Table 3, Table 6, Table 7, Table 8, Table 23, Table 24, Table 25, Table 27, Table 30, Table 32, Table 35</li> <li>■ Added Table 33</li> <li>■ Added “Fast Passive Parallel Configuration Timing”</li> <li>■ Added “Active Serial Configuration Timing”</li> <li>■ Added “Passive Serial Configuration Timing”</li> <li>■ Added “Remote System Upgrades”</li> <li>■ Added “User Watchdog Internal Circuitry Timing Specification”</li> <li>■ Added “Initialization”</li> <li>■ Added “Raw Binary File Size”</li> </ul>
June 2012	2.4	<ul style="list-style-type: none"> <li>■ Added Figure 1, Figure 2, and Figure 3.</li> <li>■ Updated Table 1, Table 2, Table 3, Table 6, Table 11, Table 22, Table 23, Table 27, Table 29, Table 30, Table 31, Table 32, Table 35, Table 38, Table 39, Table 40, Table 41, Table 43, Table 56, and Table 59.</li> <li>■ Various edits throughout to fix bugs.</li> <li>■ Changed title of document to <i>Stratix V Device Datasheet</i>.</li> <li>■ Removed document from the Stratix V handbook and made it a separate document.</li> </ul>
February 2012	2.3	<ul style="list-style-type: none"> <li>■ Updated Table 1–22, Table 1–29, Table 1–31, and Table 1–31.</li> </ul>
December 2011	2.2	<ul style="list-style-type: none"> <li>■ Added Table 2–31.</li> <li>■ Updated Table 2–28 and Table 2–34.</li> </ul>
November 2011	2.1	<ul style="list-style-type: none"> <li>■ Added Table 2–2 and Table 2–21 and updated Table 2–5 with information about Stratix V GT devices.</li> <li>■ Updated Table 2–11, Table 2–13, Table 2–20, and Table 2–25.</li> <li>■ Various edits throughout to fix SPRs.</li> </ul>
May 2011	2.0	<ul style="list-style-type: none"> <li>■ Updated Table 2–4, Table 2–18, Table 2–19, Table 2–21, Table 2–22, Table 2–23, and Table 2–24.</li> <li>■ Updated the “DQ Logic Block and Memory Output Clock Jitter Specifications” title.</li> <li>■ Chapter moved to Volume 1.</li> <li>■ Minor text edits.</li> </ul>
December 2010	1.1	<ul style="list-style-type: none"> <li>■ Updated Table 1–2, Table 1–4, Table 1–19, and Table 1–23.</li> <li>■ Converted chapter to the new template.</li> <li>■ Minor text edits.</li> </ul>
July 2010	1.0	Initial release.